

ABSTRACT

5 The present invention relates to a carrier for used in manufacturing semiconductor encapsulant packages. The carrier comprises at least one receiving part and a plurality of positioning pins; wherein the receiving part is used in receiving the semiconductor encapsulant package, and the positioning pins protrude upwards from an edge of the receiving part for used in positioning the semiconductor encapsulant package on the carrier; and each positioning pin is at an obtuse angle θ to the receiving part. The

10 present invention can prevent an encapsulant from contacting with the positioning pins and avoid leakage when applying the encapsulant. Additionally, the present invention also broadens available areas of substrates for packaging. Furthermore, the carrier in the present invention is integrally formed and has a advantage of being produced and controlled

15 easily.

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